

Abstract

Component with WLP-capable encapsulation and production process

5        It is proposed to encapsulate an electrical component with a cover and in particular with a printed circuit board, and to produce the electrical connections by means of a conductive adhesive. Said adhesive can be injected by means of a channel system into the structure in which the electrical short circuit of all connections can be re-opened by a suitably conducted saw cut during the separation of the components.

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Significant Figure: Figure 1

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